

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE4268G	**Issued**	14. September 2018
MA#	MA003606542		
Package	PG-DSO-20-66	**Weight***	486.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.950	0.61	0.61	6069	6069
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6386	
	non noble metal	copper	7440-50-8	126.041	25.93	26.61	259307	266092
wire	non noble metal	copper	7440-50-8	0.142	0.03	0.03	291	291
encapsulation	organic material	carbon black	1333-86-4	0.695	0.14		1431	
	plastics	epoxy resin	-	31.986	6.58		65804	
	inorganic material	silicondioxide	60676-86-0	314.989	64.81	71.53	648032	715267
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5649	5649
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3336	3336
glue	plastics	epoxy resin	-	0.401	0.08		824	
	noble metal	silver	7440-22-4	1.202	0.25	0.33	2472	3296
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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